

[54] SEMICONDUCTOR

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[52] U.S. Cl. **D13/99**

[58] Field of Search **D13/12, 99, 40, 41; 174/52 R, 52 PE, 52 S, 52 FP, 50.5, 50.52, 50.56; 357/70, 73, 74, 80**

[56]

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[57]

CLAIM

The ornamental design for a semiconductor, as shown.

DESCRIPTION

FIG. 1 is a right side, top and front perspective view of a semiconductor showing our new design;

FIG. 2 is a rear elevational view thereof;

FIG. 3 is a left side view thereof;

FIG. 4 is a bottom view thereof.

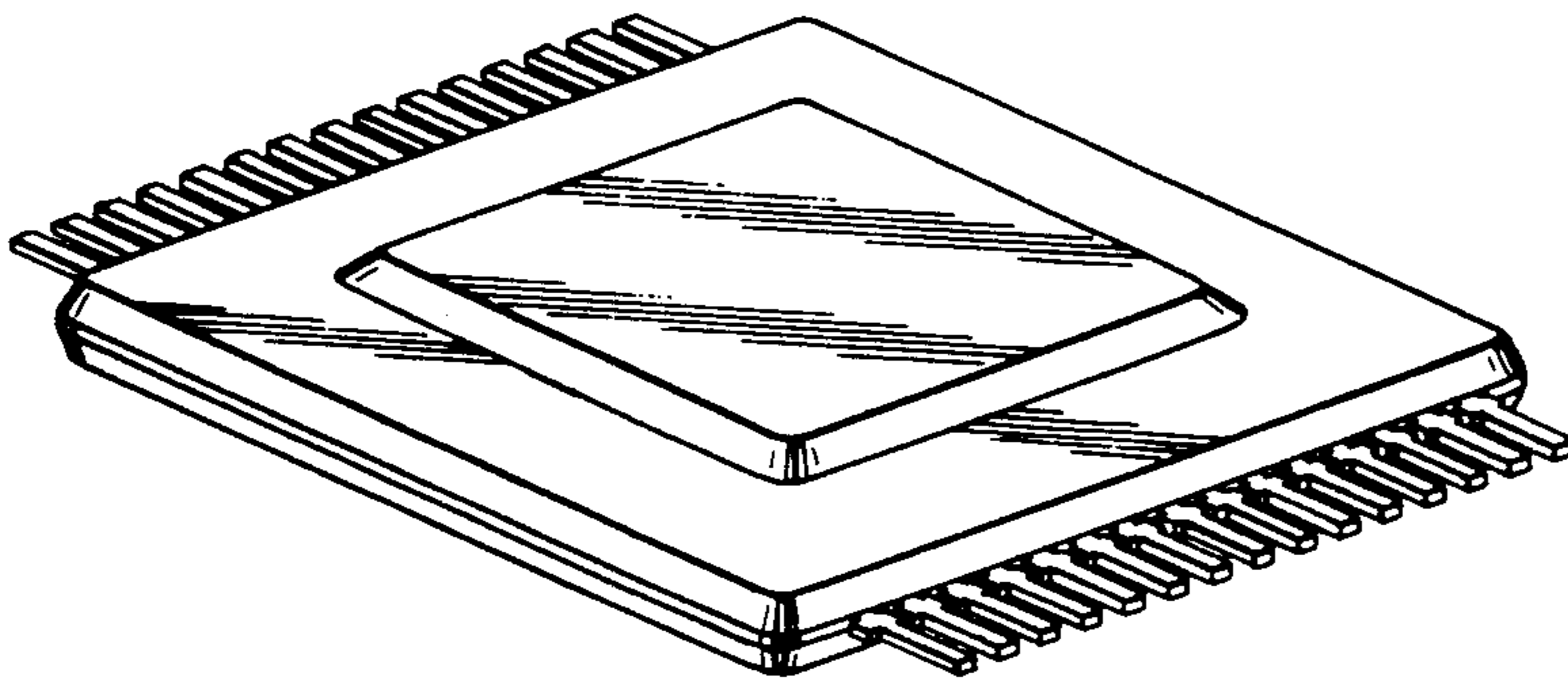


FIG. 1

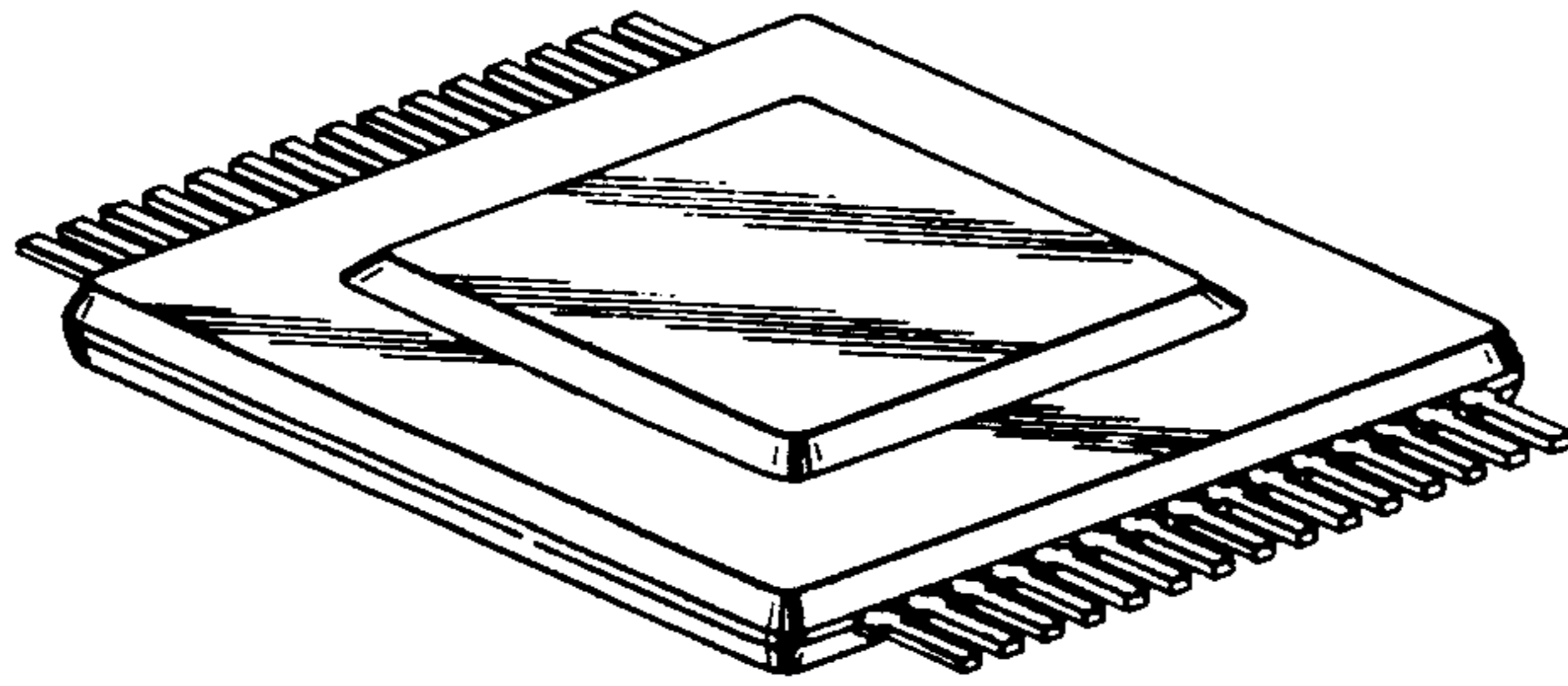


FIG. 2

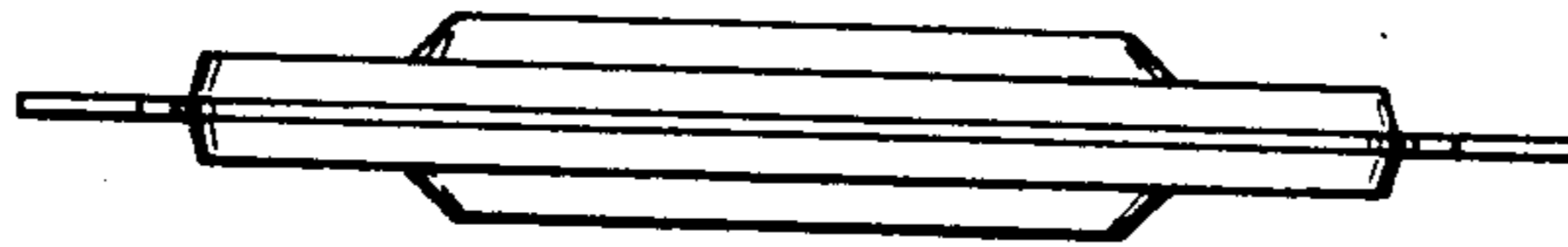


FIG. 3

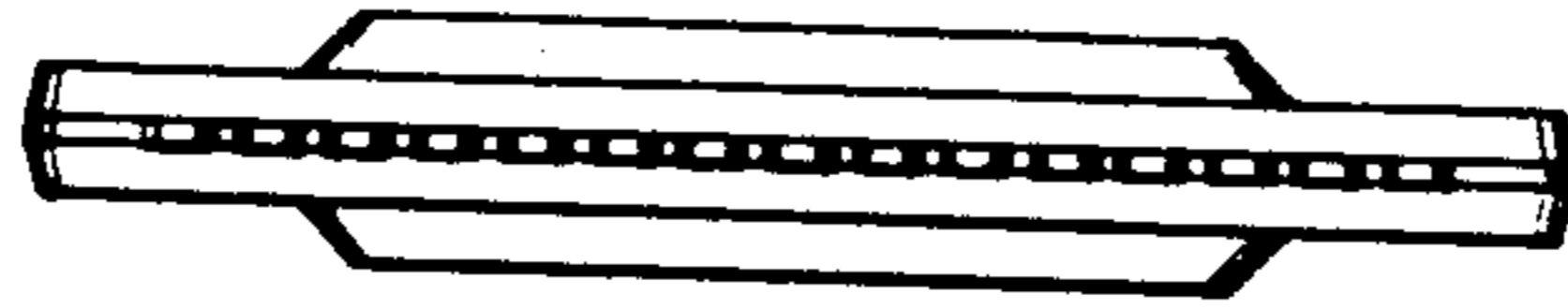


FIG. 4

